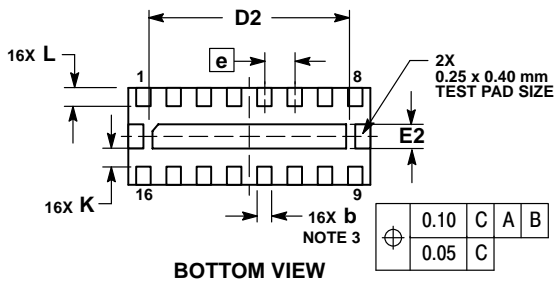
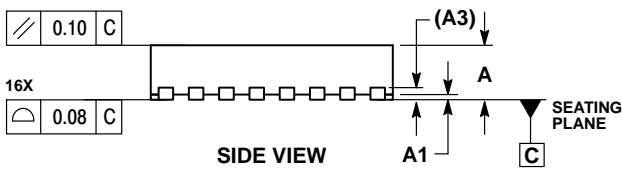
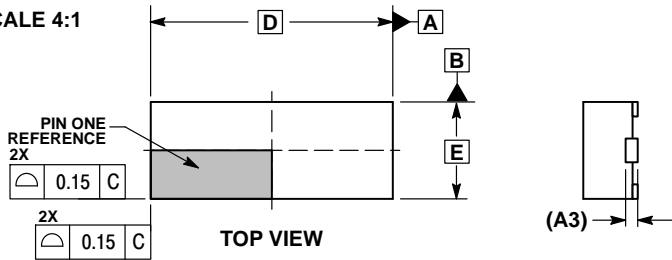


DFN16, 4x1.6, 0.5P
CASE 506AC
ISSUE D

DATE 22 AUG 2013

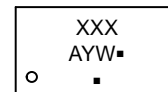
SCALE 4:1



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION b APPLIES TO TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL.
 4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

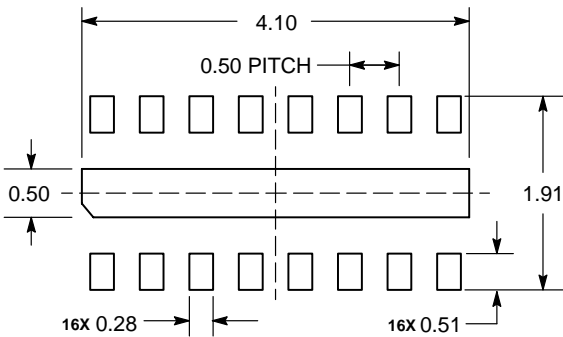
MILLIMETERS		
DIM	MIN	MAX
A	0.80	1.00
A1	0.00	0.05
A3	0.20 REF	
b	0.18	0.30
D	4.00 BSC	
D2	3.10	3.30
E	1.60 BSC	
E2	0.30	0.50
e	0.50 BSC	
K	0.20	iii
L	0.20	0.40

GENERIC MARKING DIAGRAM*



- XXX = Specific Device Code
- A = Assembly Location
- Y = Year
- W = Work Week
- = Pb iFree Package

*This information is generic. Please refer to device data sheet for actual part marking.
Pb iFree indicator, G or microdot ▪, may or may not be present.



*For additional information on our Pb iFree strategy and soldering details, please download the ON Semiconductor Soldering and